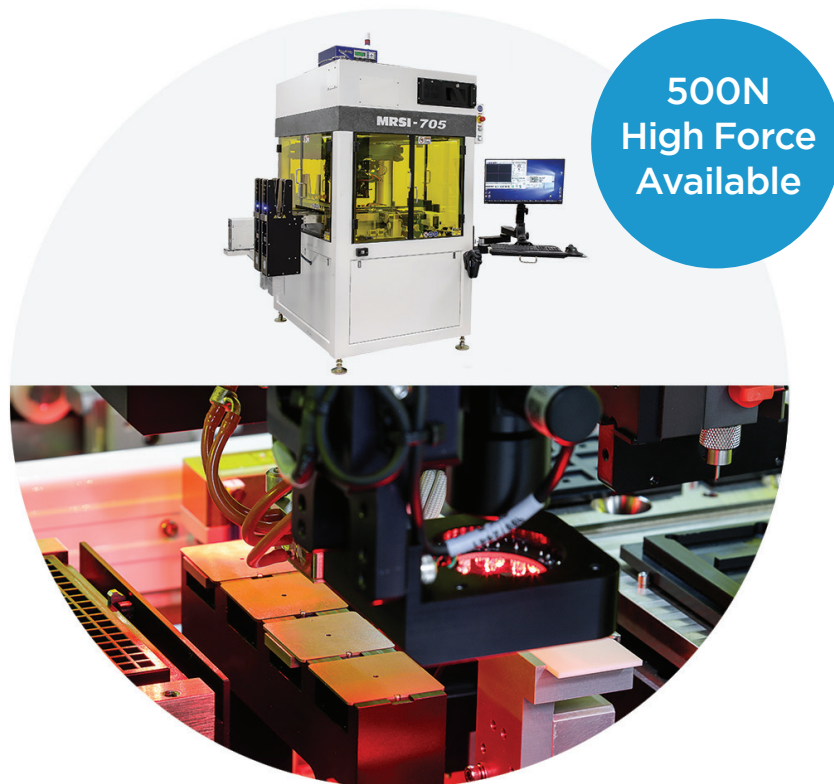


MRSI-705HF

5 MICRON HIGH FORCE DIE BONDER



Assembly Processes

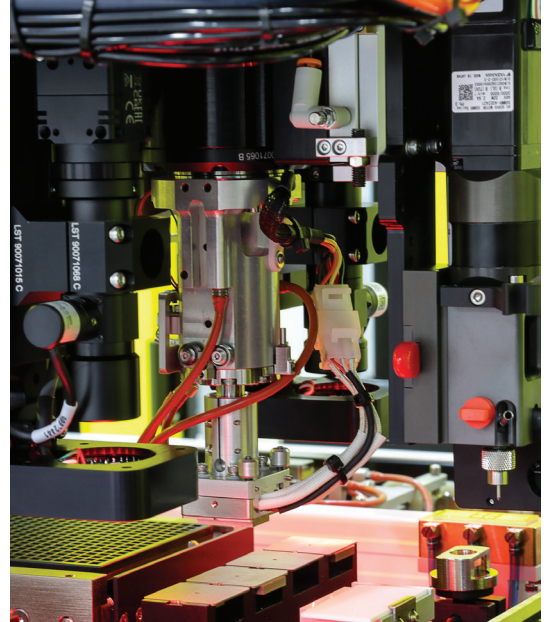
- Thermal Compression Bonding
- Sintering
- Eutectic Bonding
- Epoxy Die Attach
- In-situ UV Bonding
- Flip Chip Assembly

All-In-One Platform

- Large Configurable Work Area
- Precision Force Control
- Advanced Machine Vision
- Programmable Multi-Color Lighting
- Epoxy and Sintering Paste Dispense
- Turnkey Integrated Production Lines

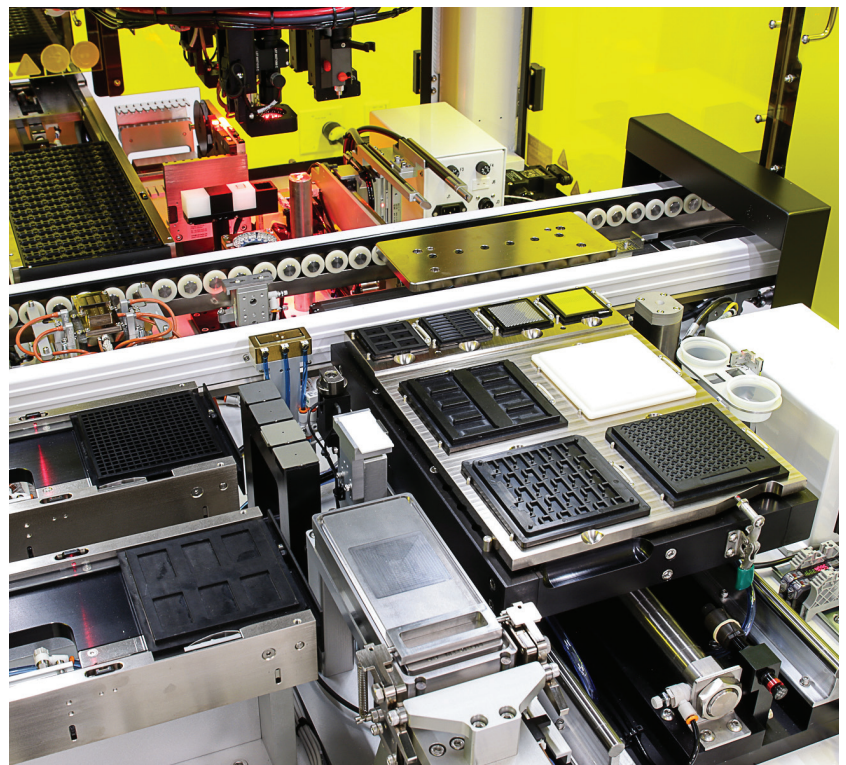
MRSI Systems has been serving optoelectronic and microelectronic customers for the past 40+ years and understands their requirement to scale efficiently in today's fast-paced marketplace.

The MRSI-705HF is equipped with a heated bond head that can apply up to 500N of force during the bonding process, while providing heating up to 400°C from the top. It is the ideal tool for advanced applications such as sintering for power semiconductors and thermocompression bonding for IC packaging.



Applications

- Medical Imaging
- CZT detectors
- Microwave Modules
- Photonics Packaging
- RF Power Amplifiers
- Infrared Sensors
- Pressure Sensors
- MEMS Devices
- Semiconductor Packaging
- Hybrid Electronics
- Multichip Modules
- Laser Diode Bonding
- Inkjet and Print Head



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